



## Material Content Data Sheet



<b>Sales Product Name</b>		ITS42K5DLDF		<b>Issued</b>		14. August 2015		
<b>MA#</b>		MA001230998						
<b>Package</b>		PG-TSON-10-2		<b>Weight*</b>		31.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.156	3.64	3.64	36386	36386
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		417	
	non noble metal	iron	7439-89-6	0.265	0.83		8348	
wire	non noble metal	copper	7440-50-8	10.773	33.90	34.78	338982	347851
	non noble metal	copper	7440-50-8	0.062	0.19	0.19	1946	1946
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.12		1172
	plastics	epoxy resin	-	1.917	6.03		60335	
	inorganic material	silicondioxide	60676-86-0	16.661	52.44	58.59	524268	585775
leadfinish	non noble metal	tin	7440-31-5	0.370	1.16	1.16	11646	11646
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2022	2022
glue	plastics	epoxy resin	-	0.114	0.36		3594	
	noble metal	silver	7440-22-4	0.343	1.08	1.44	10780	14374
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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